MA2Z784 (MA784)

Silicon epitaxial planar type

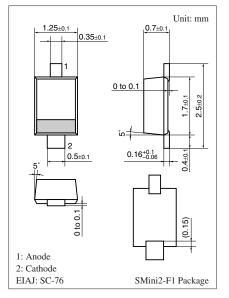
For super high speed switching For small current rectification

Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)}$ = 100 mA rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- \bullet Low forward voltage V_{F} and good rectification efficiency

	Ja		
Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Peak forward current	I _{FM}	300	mA
Forward current (Average)	I _{F(AV)}	100	mA
Non-repetitive peak forward surge current *	I _{FSM}	1	А
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: 2D

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

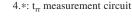
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I _R	$V_R = 30 V$			15	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		20		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2.0		ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

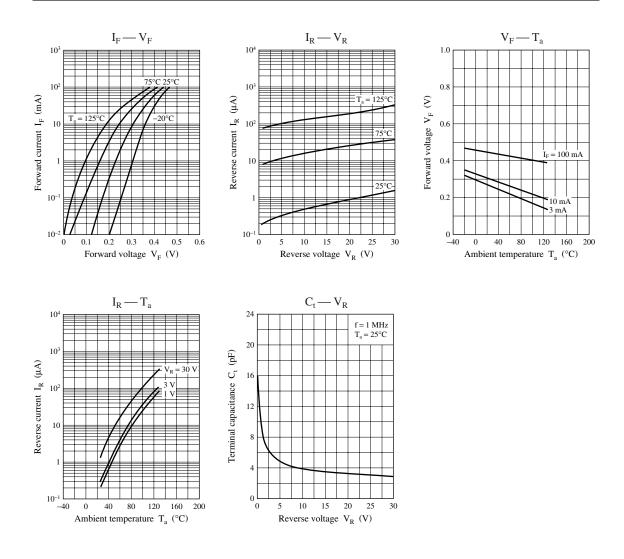
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz.



Input Pulse Bias Application Unit (N-50BU) Output Pulse +90% 0.1 L $t_p = 2 \ \mu s$ = 100 mA= 0.35 ns= 100 mAPulse Generator Wave Form Analyzer Ś = 0.05 $= 100 \Omega$ (PG-10N) (SAS-8130) $R_s = 50 \Omega$ $R_i = 50 \Omega$ Note) The part number in the parenthesis shows conventional part number.



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